TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (High speed U-MOSIII)

# ТРС8010-Н

DC-DC Converters Notebook PC Applications Portable Equipment Applications

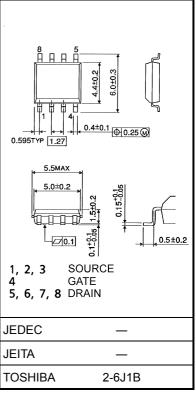
- Small footprint due to small and thin package
- High speed switching
- Small gate charge: Qg = 18 nC (typ.)
- Low drain-source ON resistance:  $R_{DS}$  (ON) = 12 m $\Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 11 \text{ S} (typ.)$
- Low leakage current:  $I_{DSS} = 10 \ \mu A \ (max) \ (V_{DS} = 30 \ V)$
- Enhancement mode:  $V_{th}$  = 1.1 to 2.3 V (V\_{DS} = 10 V,  $I_{D}$  = 1 mA)

#### Maximum Ratings (Ta = 25°C)

	Characte	ristics	Symbol	Rating	Unit	
	Drain-source voltage		V <sub>DSS</sub>	30	V	
	Drain-gate voltage (R	V <sub>DGR</sub>	30	V		
	Gate-source voltage			±20	V	
	Drain current	DC (Note 1)	Ι <sub>D</sub>	11	А	
		Pulse (Note 1)	I <sub>DP</sub>	44	~	
	Drain power dissipati	on (t = 10 s) (Note 2a)	PD	1.9	w	
	Drain power dissipati	on (t = 10 s) (Note 2b)	PD	1.0	W	
www.Datas	Single pulse avalancl	ne energy (Note 3)	E <sub>AS</sub>	157	mJ	
	Avalanche current		I <sub>AR</sub>	11	А	
	Repetitive avalanche (	energy Note 2a) (Note 4)	E <sub>AR</sub>	0.19	mJ	
	Channel temperature		T <sub>ch</sub>	150	°C	
	Storage temperature range			-55 to 150	°C	

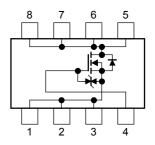
Note: For (Note 1), (Note 2), (Note 3) and (Note 4), please refer to the next page.

This transistor is an electrostatic sensitive device. Please handle with caution.



Weight: 0.080 g (typ.)

### **Circuit Configuration**

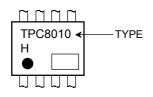


Unit: mm

### **Thermal Characteristics**

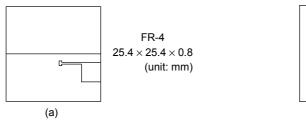
Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient $(t = 10 \text{ s})$ (Note 2a)	R <sub>th (ch-a)</sub>	65.8	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	R <sub>th (ch-a)</sub>	125	°C/W

### Marking (Note 5)

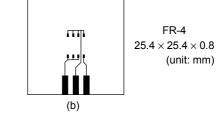


Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a)



(b) Device mounted on a glass-epoxy board (b)



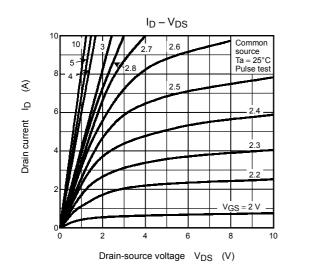
- Note 3:  $V_{DD} = 24 \text{ V}, \text{ T}_{ch} = 25^{\circ}\text{C}$  (initial), L = 1.0 mH, R<sub>G</sub> = 25  $\Omega$ , I<sub>AR</sub> = 11 A
- Note 4: Repetitive rating: pulse width limited by maximum channel temperature
- Note 5: on lower left of the marking indicates Pin 1.
- www.DataSheet4U.com shows lot number. (year of manufacture: last decimal digit of the year of manufacture, month of manufacture: January to December are denoted by letters A to L respectively.)

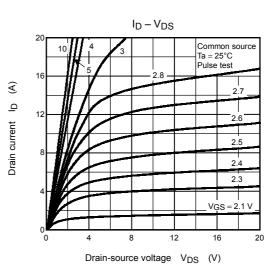
Electrical Characteristics (Ta = 25°C)

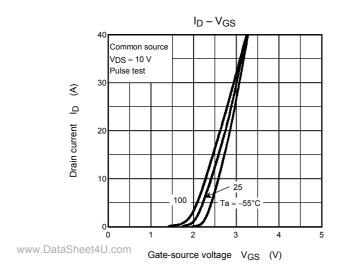
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit	
Gate leakage current		I <sub>GSS</sub>	$V_{GS}=\pm 16~V,~V_{DS}=0~V$	_		±10	μA	
Drain cut-OFF current		I <sub>DSS</sub>	$V_{DS} = 30 \text{ V}, \text{ V}_{GS} = 0 \text{ V}$		_	10	μA	
Drain-source breakdown voltage		V (BR) DSS	$I_{D} = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	30			V	
		V (BR) DSX	$I_D = 10 \text{ mA}, V_{GS} = -20 \text{ V}$	15			v	
Gate threshold voltage		V <sub>th</sub>	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 1 \text{ mA}$	1.1	_	2.3	V	
Drain-source ON resistance		Pro (ou)	$V_{GS}=4.5~V,~I_{D}=5.5~A$	_	16	25	- mΩ	
		R <sub>DS (ON)</sub>	$V_{GS} = 10 \text{ V}, \text{ I}_{D} = 5.5 \text{ A}$	_	12	16		
Forward transfer admittance		Y <sub>fs</sub>	$V_{DS} = 10 \text{ V}, \text{ I}_{D} = 5.5 \text{ A}$	5.5	11	_	S	
Input capacitance		C <sub>iss</sub>			1020	_	pF	
Reverse transfer capacitance		C <sub>rss</sub>	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		120	_		
Output capacitance		C <sub>oss</sub>		_	400	_		
Switching time	Rise time	t <sub>r</sub>	$V_{GS} \stackrel{10}{}_{0}V \qquad I_{D} = 5.5 \text{ A}$	_	3.1		- ns	
	Turn-ON time	t <sub>on</sub>			11	_		
	Fall time	t <sub>f</sub>	R = 2.7Ω		3.4			
	Turn-OFF time	t <sub>off</sub>	$V_{DD} \simeq 15 \text{ V}$ Duty $\leq$ 1%, $t_{W} = 10 \ \mu s$		23			
Total gate charge (gate-source plus gate-drain)		0	$V_{DD}\simeq 24~V,~V_{GS}=10~V,~I_{D}=11~A$		18			
		Qg	$V_{DD}\simeq 24~V,~V_{GS}=5~V,~I_{D}=11~A$		10	_		
Gate-source charge 1		Q <sub>gs1</sub>			2.6		nC	
Gate-drain ("miller") charge		Q <sub>gd</sub>	$V_{DD} \simeq 24$ V, $V_{GS} = 10$ V, $I_D = 11$ A		4.4	_		
Gate switch charge		Q <sub>SW</sub>			5.5	_		

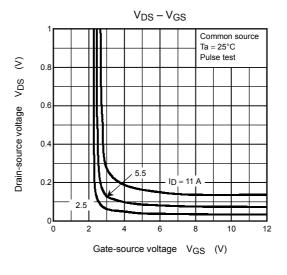
## Source-Drain Ratings and Characteristics (Ta = 25°C)

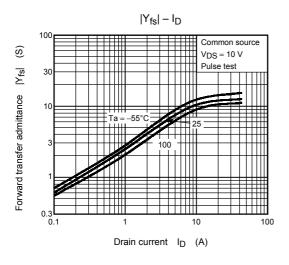
www.Data	Theet40.com Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit	
	Drain reverse current	Pulse (N	lote 1)	I <sub>DRP</sub>	—	_	_	44	А
	Forward voltage (diode)		V <sub>DSF</sub>	$I_{DR} = 11 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-1.2	V	

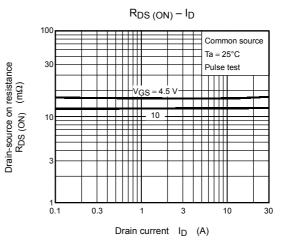


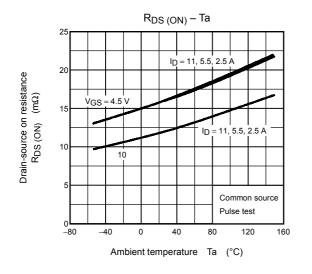


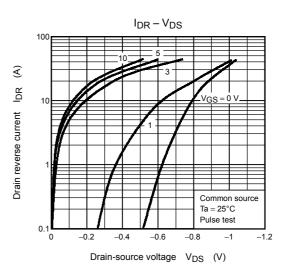


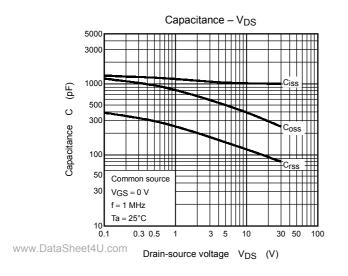


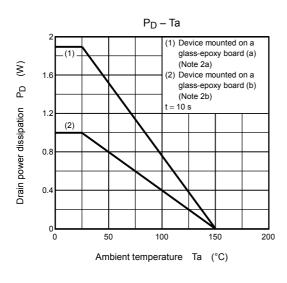


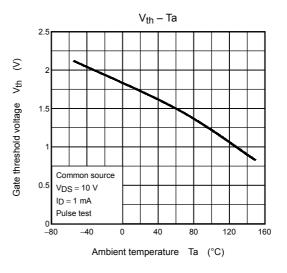


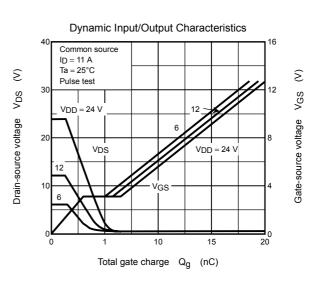


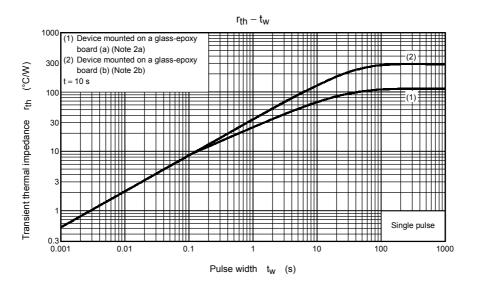




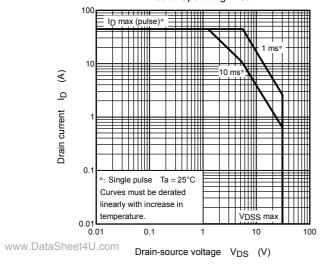








Safe Operating Area



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